REMARKS

Claims 1 and 11 have been amended to recite that the resin of the paste composition and the dielectric composition, respectively, of the present invention is a thermosetting resin selected from the group consisting of a polyimide resin and an epoxy resin, and when the thermosetting resin is an epoxy resin, the paste composition further contains a curing accelerator or a curing accelerator and a curing agent. The amendment to claims 1 and 11 is supported by the descriptions on page 22, lines 9-13, and page 22, line 21, to page 23, line 2, of the present specification.

The claims of the application are rejected in the Final Action under 35 U.S.C. § 102 as being anticipated by Matsumura et al., JP 2001-294445 ("Matsumura"), alone or when taken with Fang, US 2003/0138731, and are rejected under 35 U.S.C. § 103(a) as being unpatentable over Matsumura, alone or when taken with Fang, and in further view of various secondary references identified in the Final Action.

The claims as amended are patentable under 35 U.S.C. § 102 and 35 U.S.C. § 103(a) over the cited prior art because the primary reference, Matsumura (alone or when taken with Fang), is insufficient to support anticipation of the claims under 35 U.S.C. § 102 (or obviousness of the claims under 35 U.S.C. § 103(a)).

Matsumura does not disclose a composition containing a resin which is a polyimide resin or which is an epoxy resin with a curing accelerator or a curing agent.

Therefore, contrary to the statement in the "Response to Arguments" section of the Final Action, Matumura does not disclose compositions "made before the calcination occurs and [before] the substances 'decompose and evaporate'" (Final Action, page 8, lines 6-7) that correspond to the claimed paste composition and the claimed dielectric composition.

Furthermore, the organic substances of the composition of Matsumura, as described in paragraphs [0020] and [0024] of Matsumura, are required to be decomposed and evaporated during calcination. Therefore, it would not have been obvious for a person of ordinary skill in the art to have modified the composition of Matumura to use a polyimide resin or to use a curing accelerator or a curing agent with the glycidyl acrylate copolymer described in Matsumura. Polyimide resins are highly thermal resistant and are not "quickly heat-decomposing and evaporative" as required in Matsumura (paragraph [0020]). The use of a curing accelerator or a curing agent with the glycidyl acrylate copolymer binder resin substance of Matsumura to decompose and evaporate.

Removal of the 35 U.S.C. § 102 and 35 U.S.C. § 103(a) rejections and a notice of allowability of the claims of the application are believed to be in order and is respectfully solicited.

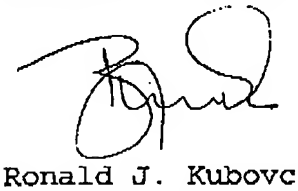
The foregoing is a complete and proper response to the Office Action dated January 21, 2009.

In the event that this paper is not considered to be timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to Deposit Account No. 111833.

In the event any additional fees are required, please also charge our Deposit Account No. 111833.

Respectfully submitted,

KUBOVCIK & KUBOVCIK



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